

 $3.5 \times 2.8 \text{ mm PLCC2 SMD LED}$

Features

- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 2000pcs/ Reel
- \bullet MSL (Moisture Sensitivity Level): 3
- Halogen-free
- RoHS compliant



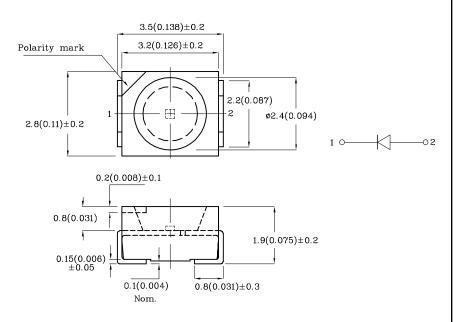




ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE

DEVICES

Package Schematics



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)	Blue (InGaN)	Unit		
Reverse Voltage	V_{R}	5	V	
Forward Current	I_{F}	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	100	mA	
Power Dissipation	P_D	120	mW	
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85		
Electrostatic Discharge Threshold (HBM)	250	V		

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Operating Characteristics (T _A =25°C)		Blue (InGaN)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	3.3	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	4	V
Reverse Current (Max.) $(V_R=5V)$	I_{R}	50	μА
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λР	465*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =20mA)	λD	470*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$\triangle \lambda$	22	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	100	pF

Part Number	Emitting Color	Emitting Material	Lens-color	CIE12' (I _F =2	s Intensity 7-2007* 0mA) cd	Wavelength CIE127-2007* nm λP	Viewing Angle 2θ 1/2
				min.	typ.		
XZFBB45S	Blue	InGaN	Water Clear	300*	447*	465*	120°

^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

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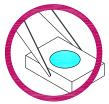


Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

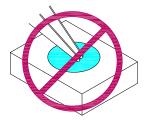
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

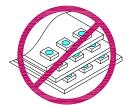


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

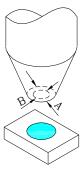




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.

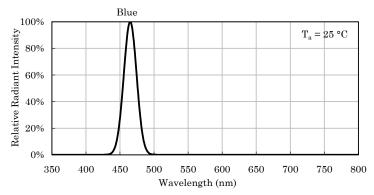


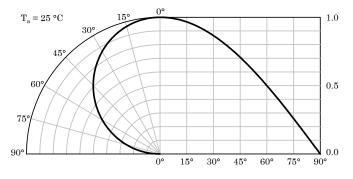
5. As silicone encapsulation is permeable to gases, some corrosive substances such as H₂S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

Mar 01,2023 XDSB4878 V8-Z Layout: Maggie L.





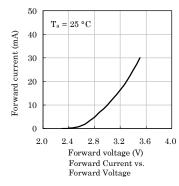


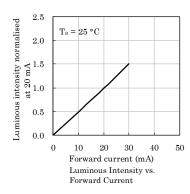


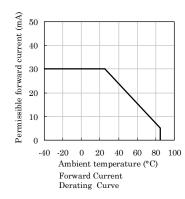
Relative Intensity Vs. CIE Wavelength

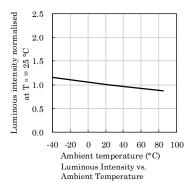
Spatial Distribution

♦ Blue



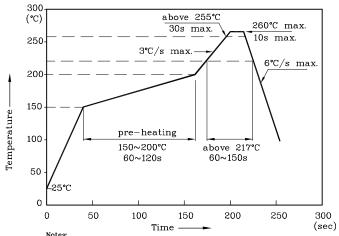






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)



- 1. All temperatures refer to the center of the package,
- measured on the package body surface facing up during reflow.

 2. Do not apply any stress to the LED during high temperature conditions.
- 3. Maximum number of soldering passes: 2

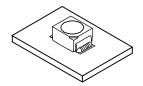


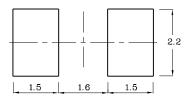




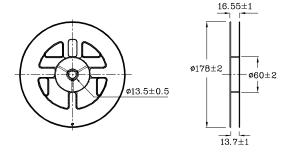
❖ The device has a single mounting surface. The device must be mounted according to the specifications.

♦ Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

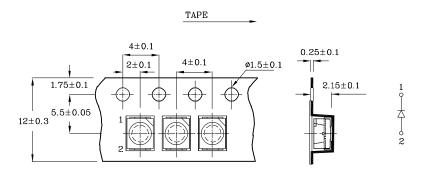




❖ Reel Dimension (Units:mm)



❖ Tape Specification (Units:mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

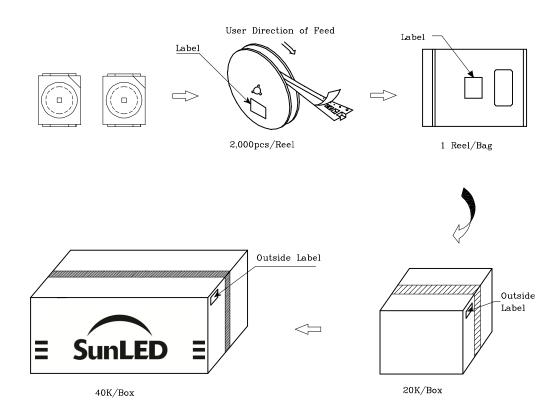
- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

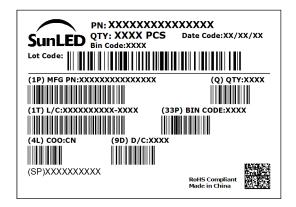
Note: Accuracy may depend on the sorting parameters.





PACKING & LABEL SPECIFICATIONS





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